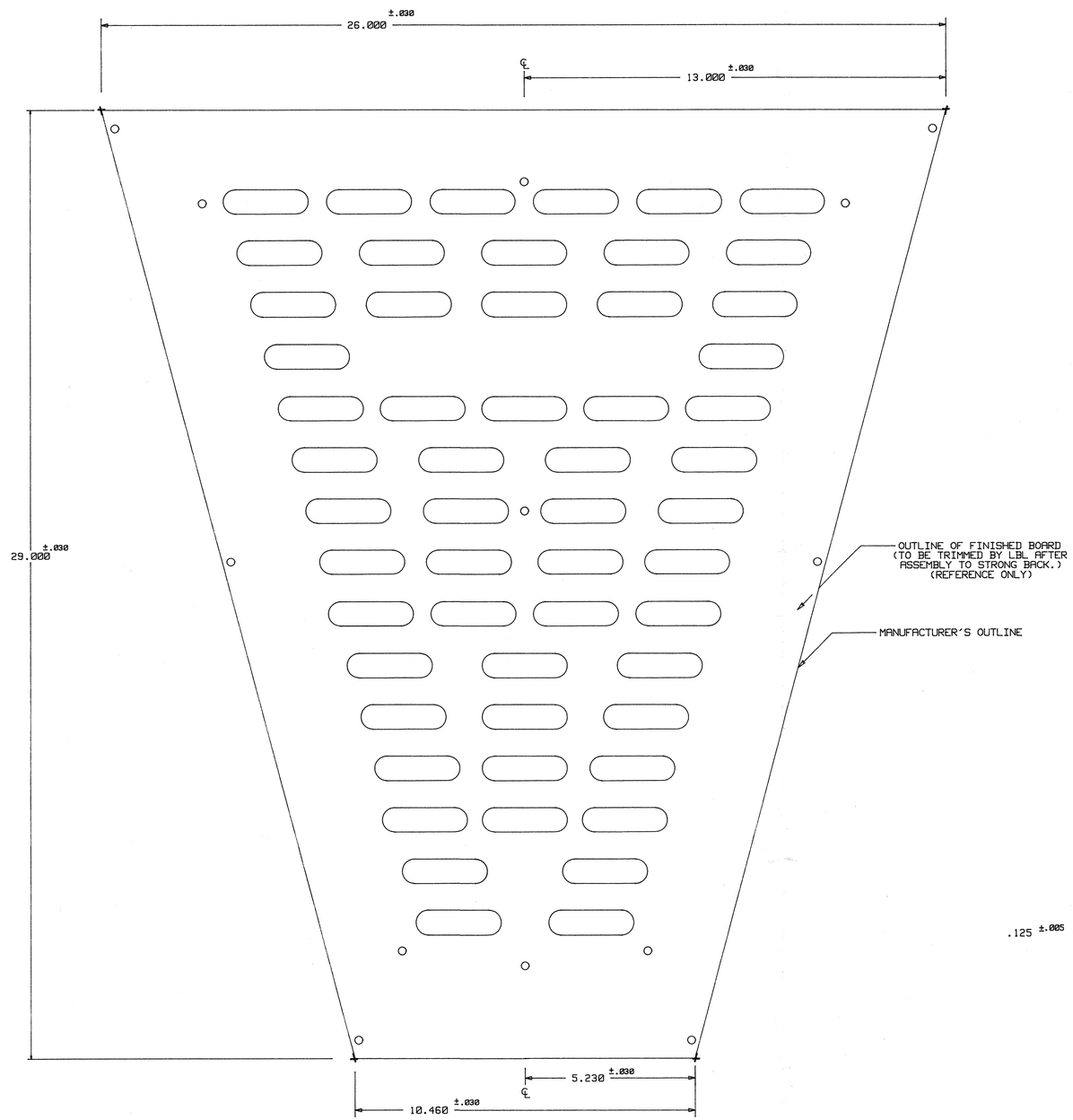
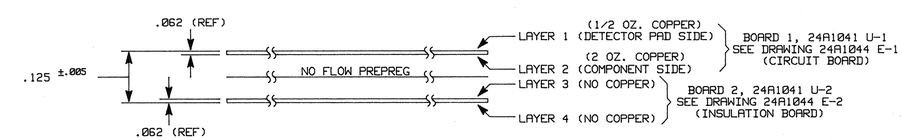
REV.	CHANGES	DRAWN	DATE	CHKD.	DATE



VIEWED FROM CONNECTOR SIDE
WITH INSULATION BOARD

NOTES:

1. BOARD MATERIAL:
   A) BOARD 1 (CIRCUIT BOARD) - .062 NEMA G10, NON FR4, GLASS EPOXY PER MIL-P-13949E FL-GFN 062C-2/.5-A1A (2 OZ. COPPER - COMPONENT SIDE AND 1/2 OZ. COPPER - DETECTOR PAD SIDE).
   B) BOARD 2 (INSULATION BOARD) - .062 NEMA G10, NON FR4, GLASS EPOXY PER MIL-P-13949E FL-GFN 062C-.5/.5-A1A (1/2 OZ EACH SIDE, ETCHED AWAY)
2. THERE IS NO TIN PLATING ON BOARDS 1 AND 2.
3. THIS IS A MULTILAYER BOARD CONSISTING OF TWO .062 THICK NEMA G10, NON FR4, GLASS EPOXY. TOTAL THICKNESS OF BOARD TO BE .125 +/-.005. DIMENSIONS ARE IN INCHES.
4. PREPREG TO BE NO FLOW TYPE.
5. ARTWORK TO BE PLOTTED ON GLASS FOR STABILITY.
6. REFERENCE DRAWINGS:
   24A1044 E-1 a000886e1 HOLE SCHEDULE - CIRCUIT BOARD
   24A1044 E-2 a000886e2 ROUTING SCHEDULE - INSULATION BOARD



PRELIMINARY

DIST I:	TITLE STAR TPC		
II:	INNER SECTOR		
III:	PAD PLANE INNER SECTOR BOARD - 2 LAYER		
SHOWN ON	BOARD OUTLINE (a000886u1 & a000886u2)		
ACCOUNT NUMBER 8052-24	DRAWN STIRKKINEN DATE 09/28/93	LAWRENCE BERKELEY LABORATORY	
SERIAL NUMBER	CHECKED DATE	UNIVERSITY OF CALIFORNIA	
DATE ISSUED / NO. REQD.	APPROVED DATE	OFFICE OF ELECTRONICS ENGINEERING	
DATE REQD.	ENGINEER THOMAS NOGGLE	FILE NO. a000886m1 / SIZE 4 / DRAWING NO. 24A1044 M-1	REV.
DEL. TO	SCALE NONE	E2,E7,E14	SHEET 1 OF 1

SEPTEMBER 28, 1993